

JOC827X Series

Rev.A.1.0

DESCRIPTION:

The products are transistor opto-couplers in a plastic DIP8 package with different lead forming options. The device is a photoelectric coupler composed of light-emitting diode and phototransistor. The products are widely used in switching power supply, intelligent meter, industrial control, measuring instruments, office equipment such as copiers, household appliances: such as air conditioners, fans, water heaters, etc.

MAIN FEATURES

High isolation 5000 VRMS

Operating temperature range -55°C to 110°C

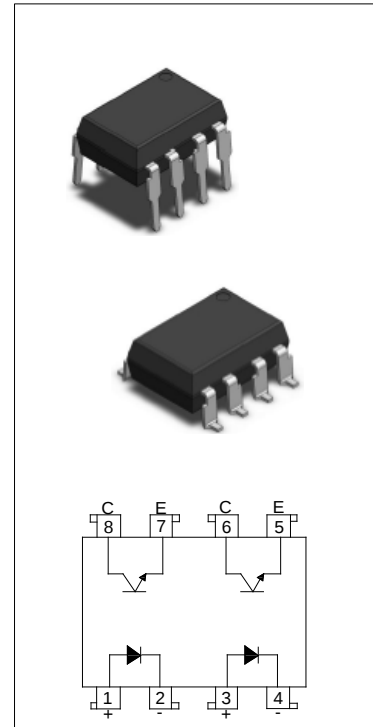
RoHS & REACH Compliance

HBM: H3A; MM: M4; CDM:C3

CQC approved

VDE approved

UL approved



ABSOLUTE MAXIMUM RATINGS (Temperature=25°C)

Parameter		Symbol	Value	Unit
Input	Forward Current	I_F	50	mA
	Peak Forward Current	I_{FP}	1 ^①	A
	Reverse Voltage	V_R	6	V
	Power Dissipation	P_D	75	mW
Output	Collector-emitter Voltage	V_{CEO}	80	V
	Emitter-collector Voltage	V_{ECO}	6	V
	Collector Current	I_C	50	mA
	Power Dissipation	P_C	150	mW
Total Power Dissipation		P_{tot}	225	mW
Isolation Voltage		V_{iso}	5000 ^②	Vrms
Operating Temperature		T_{opr}	-55~+110	°C
Junction Temperature		T_j	125	°C
Storage Temperature		T_{stg}	-55~+125	°C
Soldering Temperature		T_{sol}	260	°C

NOTE1: 1 μ s pulse

NOTE2: AC for 1minute, R.H.=40~60%

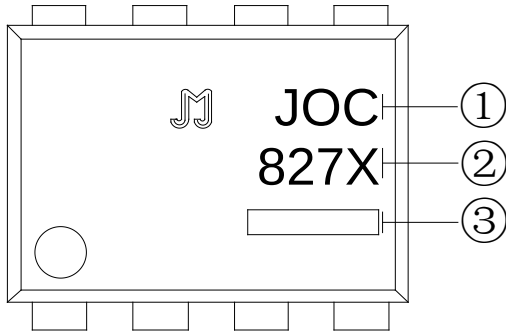
ELECTRICAL CHARACTERISTICS (Temperature=25°C)

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	V_F	$I_F=10\text{mA}$	-	1.2	1.5	V
	Reverse Current	I_R	$V_R=6\text{V}$	-	-	1	μA
	Terminal Capacitance	C_t	$V=0$, $f=1\text{MHz}$	-	30	250	pF
Output	Collector-Emitter dark current	I_{CEO}	$V_{CE}=20\text{V}$, $I_F=0$	-	-	50	nA
	Collector-Emitter breakdown voltage	BV_{CEO}	$I_C=0.1\text{mA}$ $I_F=0$	80	-	-	V
	Emitter-Collector breakdown voltage	BV_{ECO}	$I_E=0.1\text{mA}$ $I_F=0$	6	-	-	V
Transfer Characteristics	Current transfer ratio	CTR ^①	$I_F=5\text{mA}$ $V_{CE}=5\text{V}$	80	-	600	%
	Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$I_F=20\text{mA}$ $I_C=1\text{mA}$	-	0.06	0.2	V
	Isolation resistance	R_{IO}	DC500V 40~60%R.H.	5×10^{10}	10^{11}	-	Ω
	Floating Capacitance	C_{IO}	$V=0$, $f=1\text{MHz}$	-	0.6	1	pF
	Cut-off Frequency	f_c	$V_{CE}=5\text{V}$, $I_C=2\text{mA}$ $R_L=100\Omega$, -3dB	-	80	-	kHz
	Rise Time	t_r	$V_{CE}=5\text{V}$, $I_C=2\text{mA}$	-	4	18	μs
	Fall Time	t_f	$R_L=100\Omega$	-	3	18	μs

NOTE1: Rank Table of Current Transfer Ratio (Temperature=25°C)

Grade Sign	Min. (%)	Max. (%)
None	80	600
A	80	160
B	130	260
C	200	400
D	300	600
E	400	600
Q	100	200

ORDERING AND MARKING INFORMATION

MARKING INFORMATION			
		① : Company Abbr. ② : Part Number & Rank ③ : Production Information Code	
Packing Quantity			
Option	Quantity	Quantity – Inner box	Quantity –Outer box
DIP	50 Units/Tube	40 Tubes/Inner box	5 Inner box/Outer box =10k Units
SMD	1200 Units/Reel	2 Reels/Inner box	5 Inner box/Outer box =12k Units

Characteristics Curves

FIG.1: Max. Allowable LED Forward Current vs. Ambient Temperature

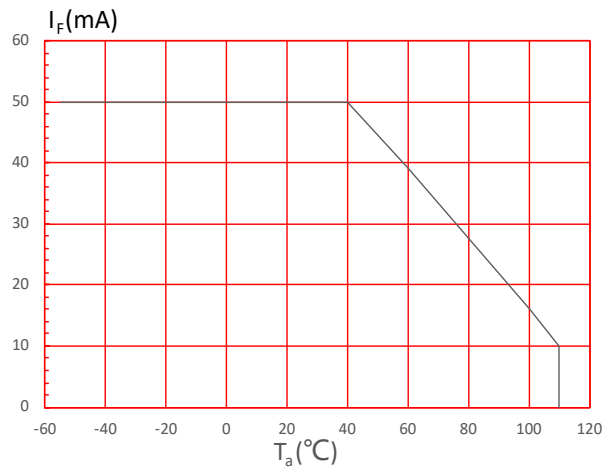


FIG.2: Collector Power Dissipation vs. Ambient Temperature

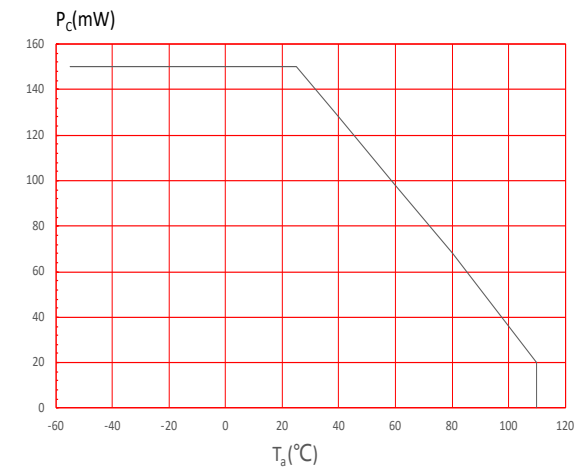


FIG.3: Forward Current vs. Forward Voltage

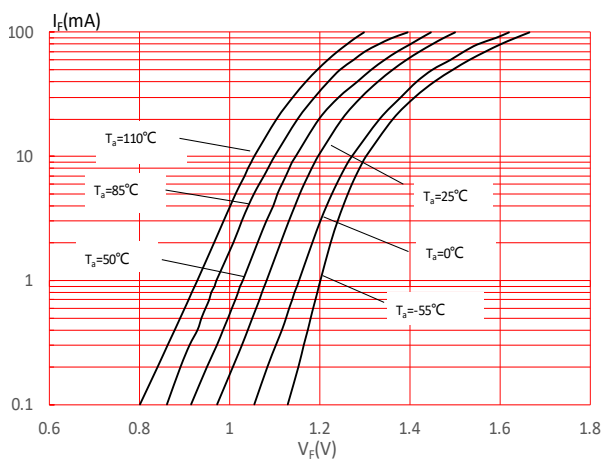


FIG.4: Normalized Collector Dark Current vs. Ambient Temperature

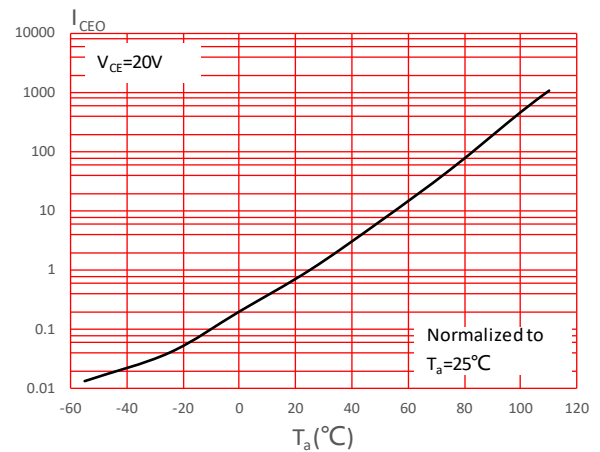


FIG.5: Collector Current vs. Collector-emitter Voltage

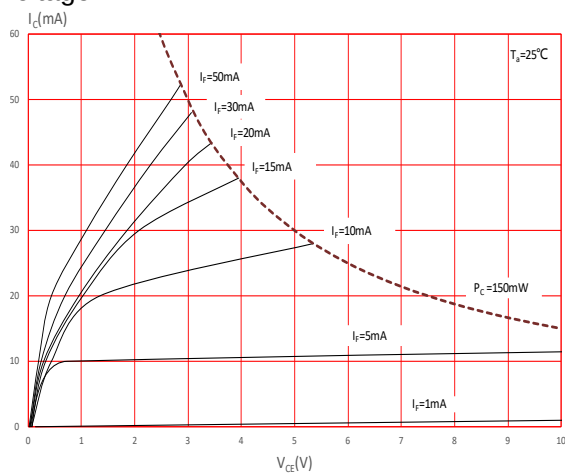


FIG.6: Normalized Current Transfer Ratio vs. Forward Current

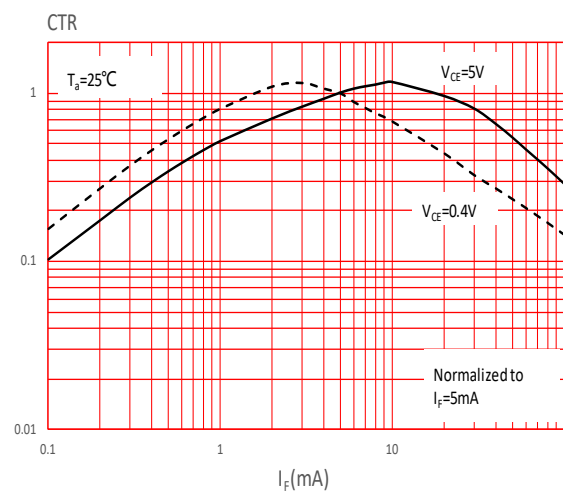
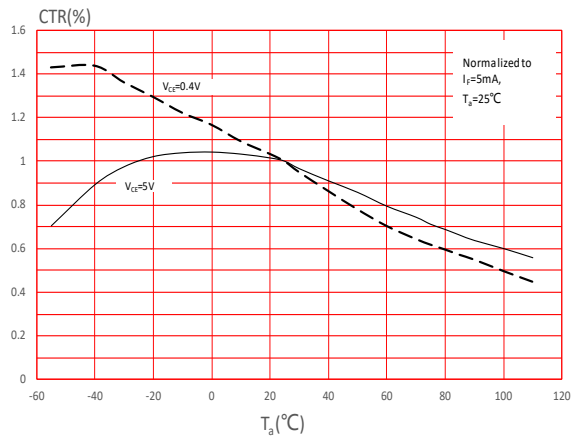
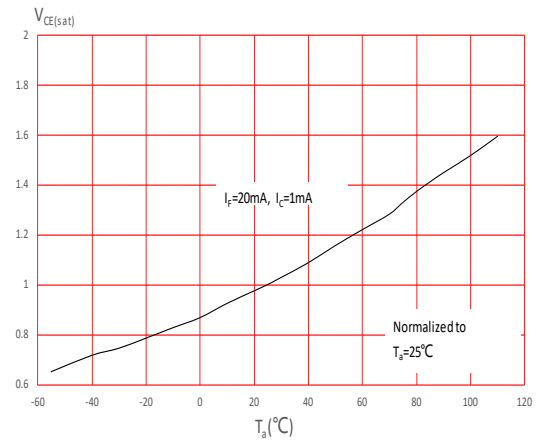
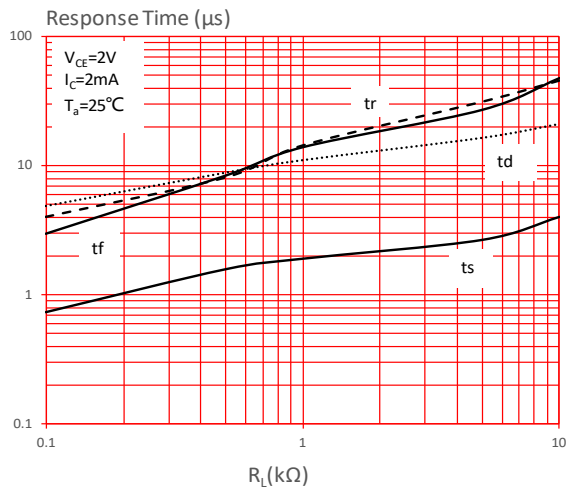
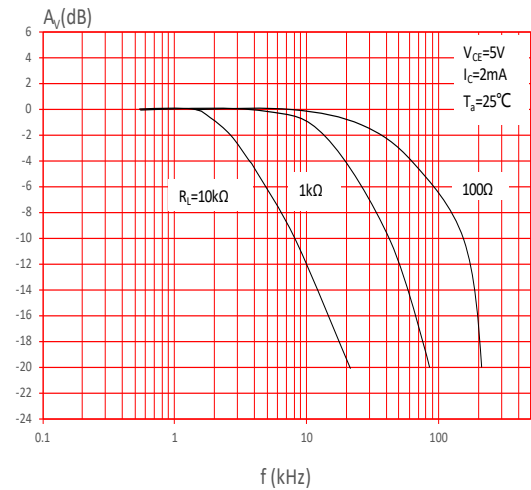
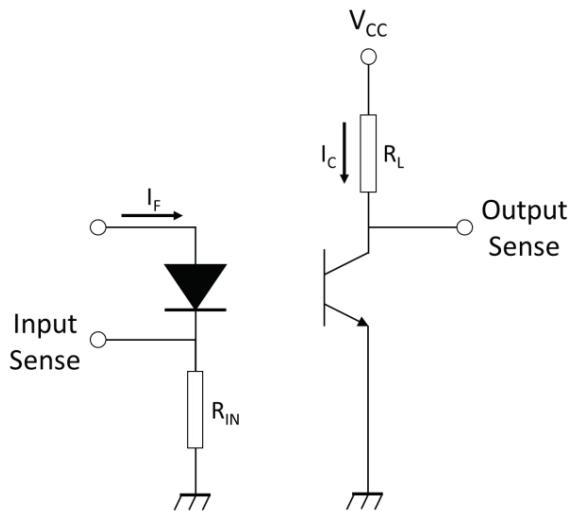
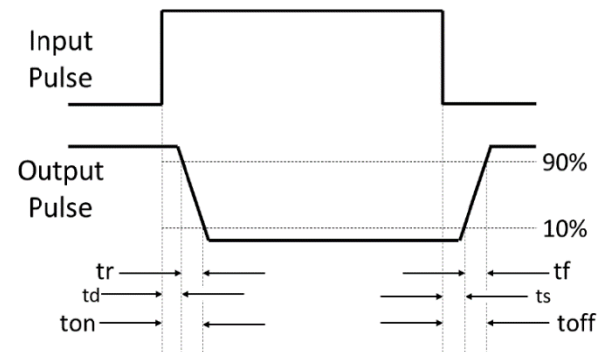
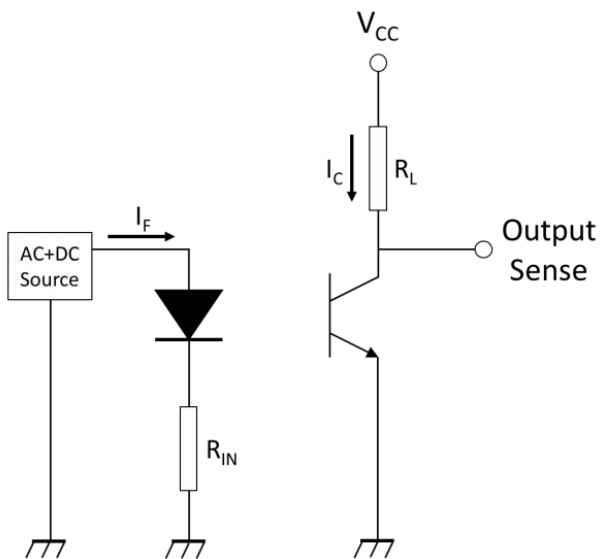


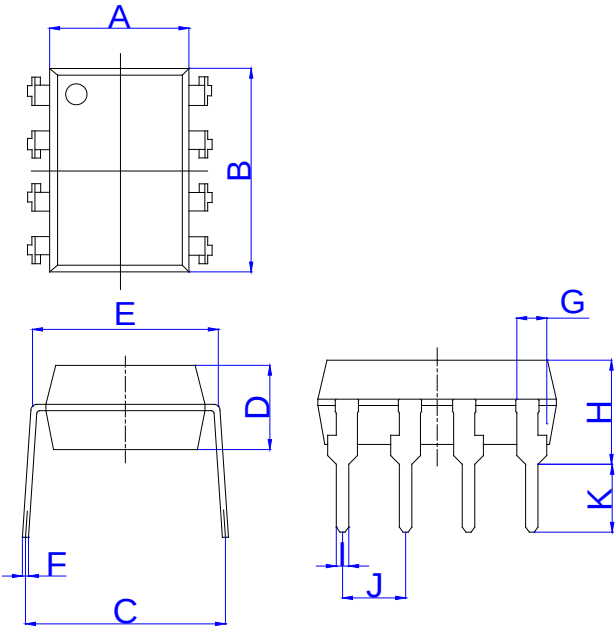
FIG.7: Normalized Current Transfer Ratio vs. Ambient Temperature

FIG.8: Normalized Collector-emitter Saturation Voltage vs. Ambient Temperature

FIG.9: Response Time vs. Load Resistance

FIG.10: Frequency Response


Test Circuits

FIG.11: Test Circuits of Response Time

FIG.12: Curves of Response Time

FIG.13: Test Circuits of Frequency Response


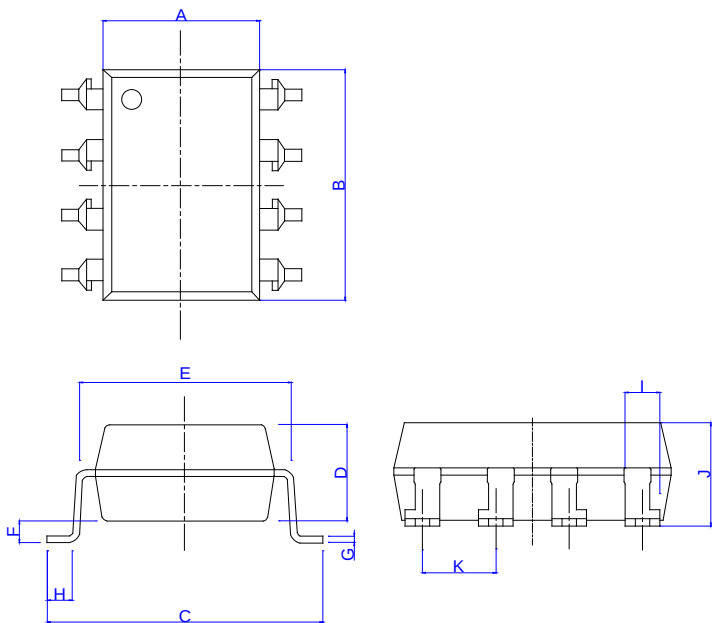
Package Dimension (Unit: mm)

Standard DIP Type:

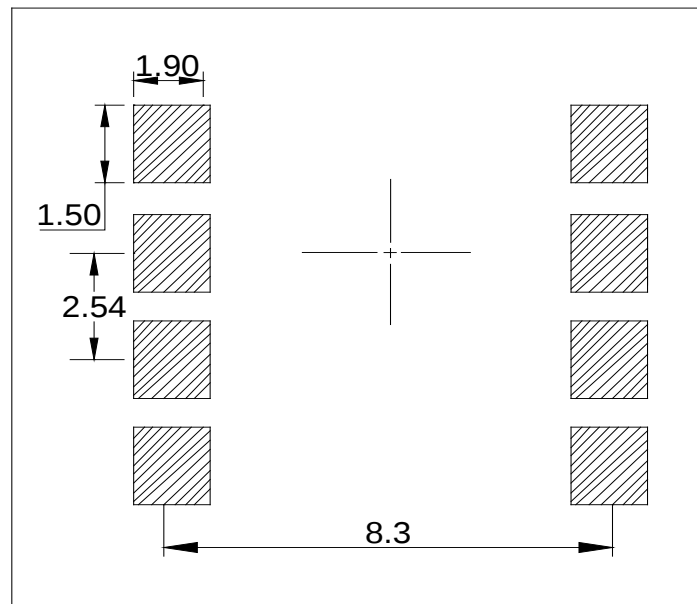
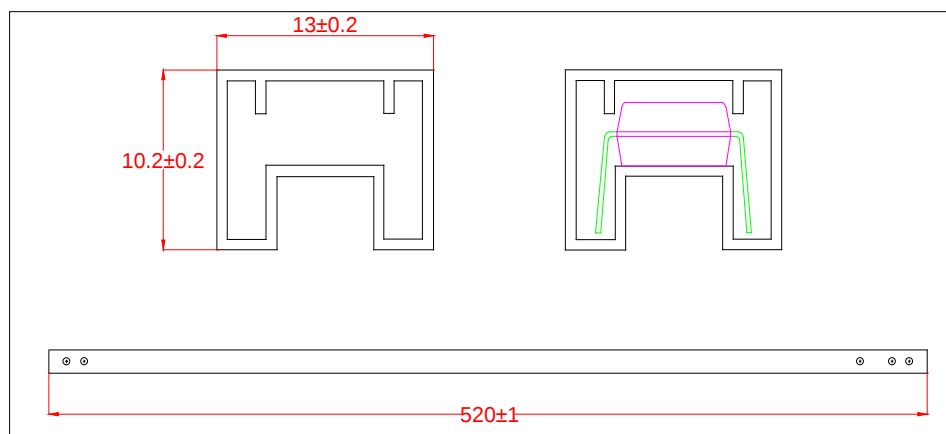


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.60	0.244		0.260
B	9.40		9.80	0.370		0.386
C	7.15		8.95	0.281		0.352
D	3.20		3.60	0.126		0.142
E	7.32		7.92	0.288		0.312
F	0.15		0.35	0.006		0.014
G	0.90		1.50	0.035		0.059
H	3.90		4.50	0.154		0.177
I	0.40		0.60	0.016		0.024
J	2.29		2.79	0.090		0.110
K	2.24		3.24	0.088		0.128

Option SMD Type:

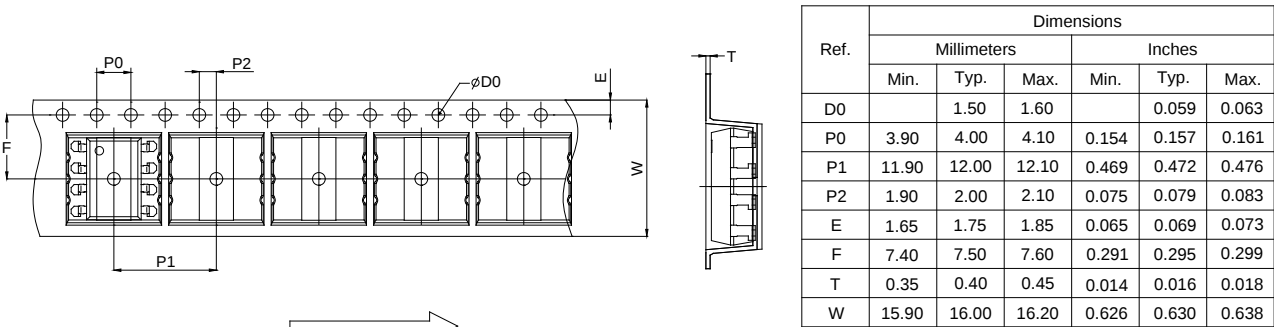


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.60	0.244		0.260
B	9.40		9.80	0.370		0.386
C	9.50		10.50	0.374		0.413
D	3.20		3.60	0.126		0.142
E	7.32		7.92	0.288		0.312
F	0.05		0.35	0.002		0.014
G	0.16		0.36	0.006		0.014
H	0.60		1.40	0.024		0.055
I	0.90		1.50	0.035		0.059
J	3.30		3.90	0.130		0.154
K	2.29		2.79	0.090		0.110

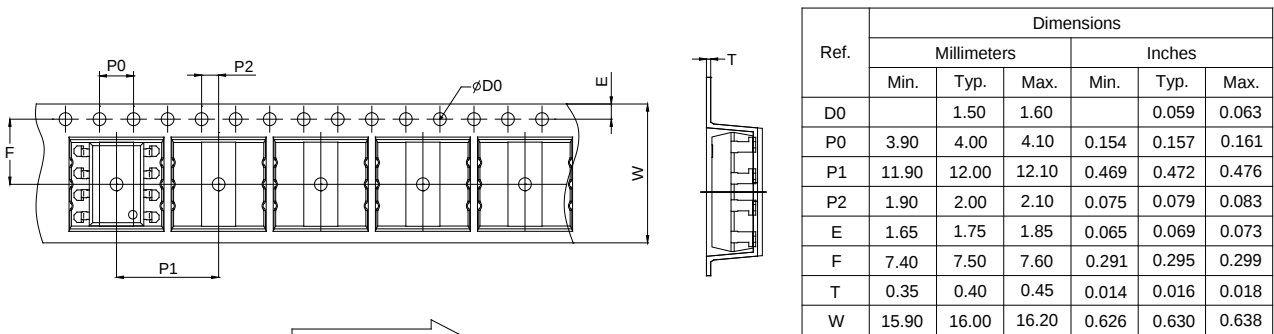
RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)**TUBE SPECIFICATIONS (Dimensions in mm unless otherwise stated)****Standard DIP**

CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

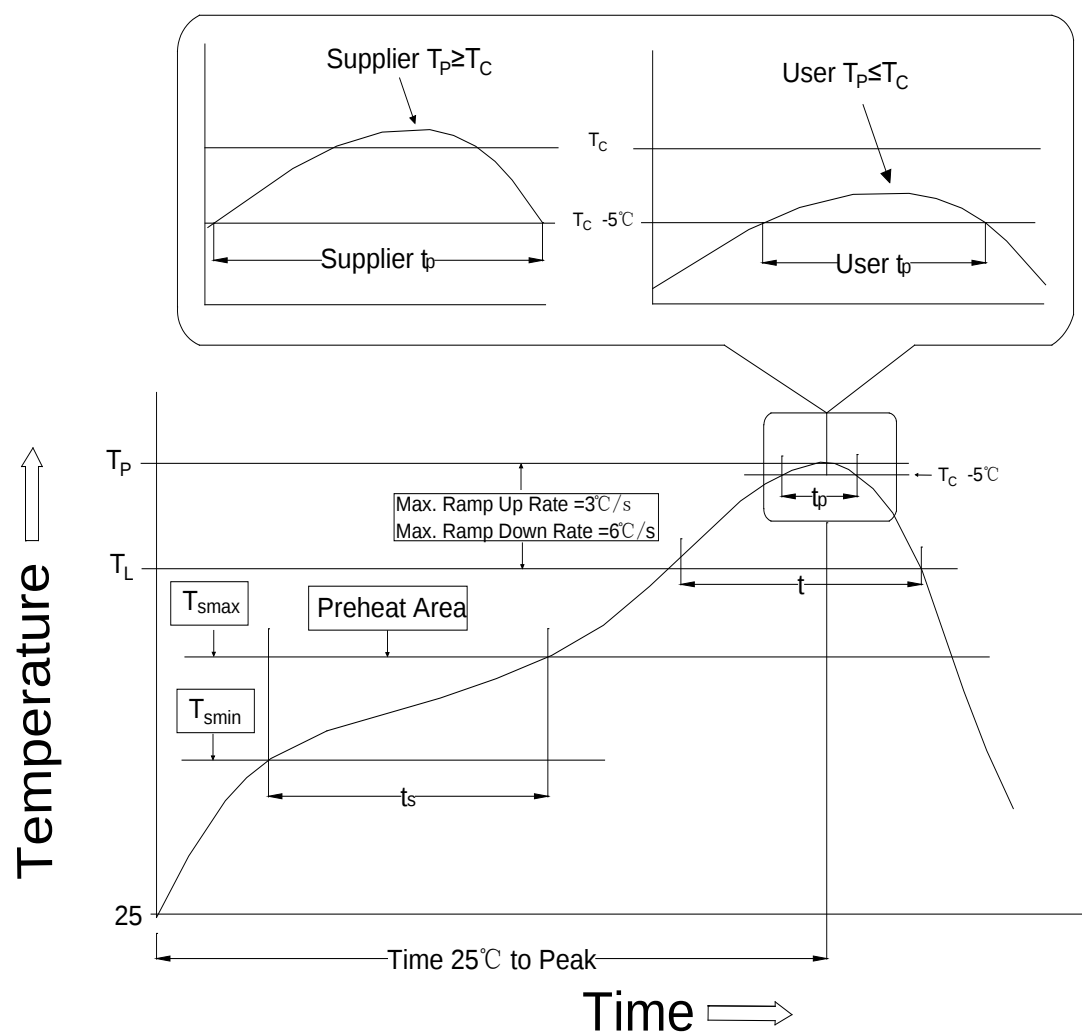
Option T3



Option T4

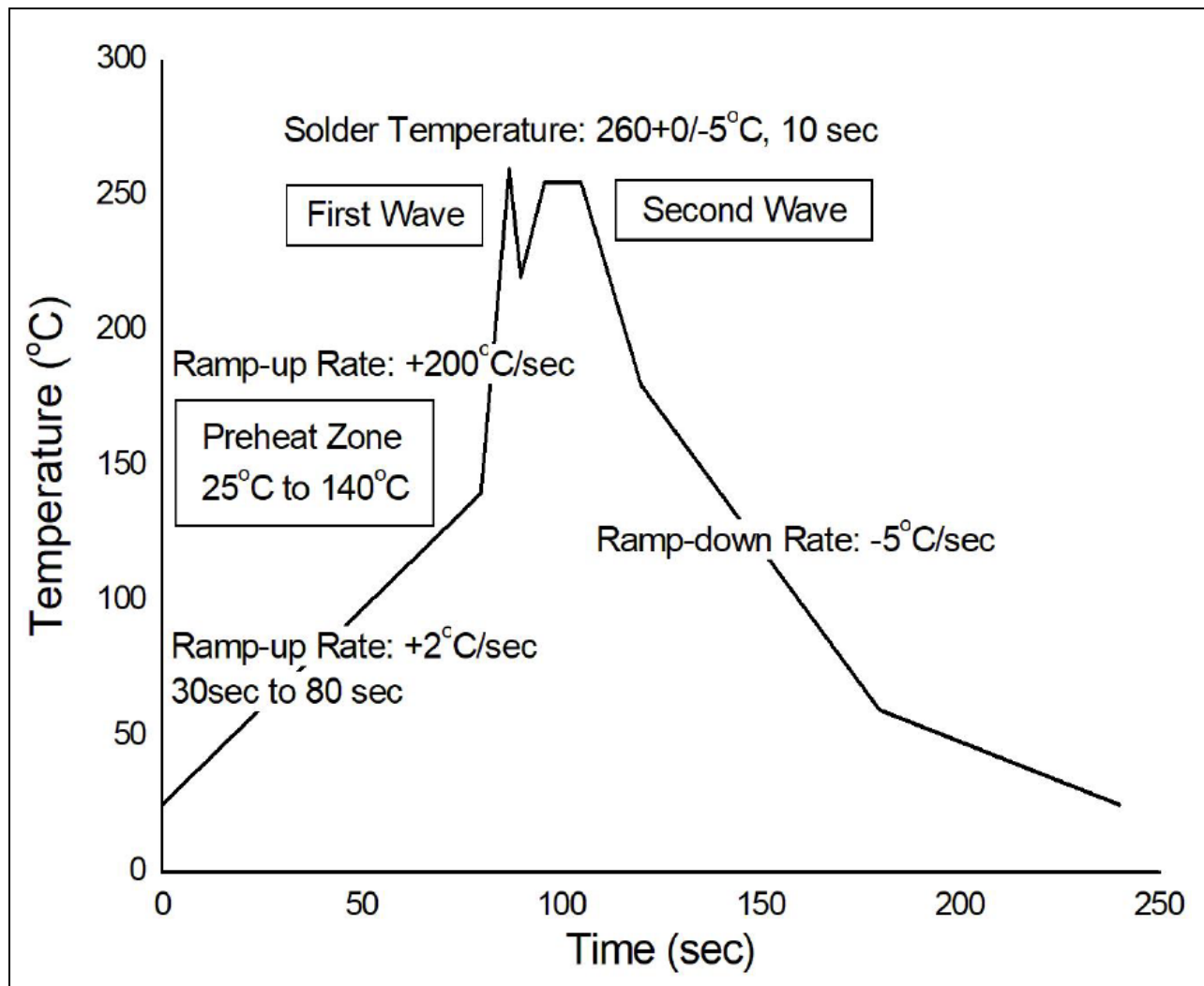


REFLOW INFORMATION



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (T_{smin})	100°C	150°C
Temperature Max. (T_{smax})	150°C	200°C
Time (t_s) from (T_{smin} to T_{smax})	60-120 seconds	60-120 seconds
Ramp-up Rate (t_L to t_P)	3°C/second max.	3°C/second max.
Liquidus Temperature (T_L)	183°C	217°C
Time (t_L) Maintained Above (T_L)	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235°C+0°C/-5°C	260°C+0°C/-5°C
Time (t_P) within 5°C of 260°C	10 seconds	10 seconds
Ramp-down Rate (T_P to T_L)	3-6°C/second	3-6°C/second
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

WAVE SOLDERING



HAND SOLDERING BY SOLDERING IRON

Soldering Temperature	360±5°C
Soldering Time	3s max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.
4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.
5. The component has a shelf life of one year when stored under standard conditions.
6. Recommend storage Temp.: 0~40°C;
Recommend storage humidity: <60%;
MSL level: MSL 1

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